

IRLR8726PBF Datasheet



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	IRLR8726PBF-DG
Manufacturer	Infineon Technologies
Manufacturer Product Number	IRLR8726PBF
Description	MOSFET N-CH 30V 86A DPAK
Detailed Description	N-Channel 30 V 86A (Tc) 75W (Tc) Surface Mount TO-252AA (DPAK)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

IRLR8726PBF

Series:

HEXFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

30 V

Drive Voltage (Max Rds On, Min Rds On):

4.5V, 10V

Vgs(th) (Max) @ Id:

2.35V @ 50µA

Vgs (Max):

±20V

FET Feature:

-

Operating Temperature:

-55°C ~ 175°C (Tj)

Supplier Device Package:

TO-252AA (DPAK)

Manufacturer:

Infineon Technologies

Product Status:

Discontinued at Digi-Key

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

86A (Tc)

Rds On (Max) @ Id, Vgs:

5.8mOhm @ 25A, 10V

Gate Charge (Qg) (Max) @ Vgs:

23 nC @ 4.5 V

Input Capacitance (Ciss) (Max) @ Vds:

2150 pF @ 15 V

Power Dissipation (Max):

75W (Tc)

Mounting Type:

Surface Mount

Package / Case:

TO-252-3, DPAK (2 Leads + Tab), SC-63

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

International
IR Rectifier

PD - 97146A

IRLR8726PbF
IRLU8726PbF

Applications

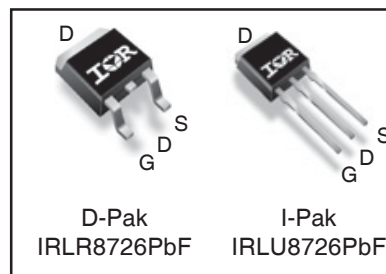
- High Frequency Synchronous Buck Converters for Computer Processor Power
- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use

Benefits

- Very Low $R_{DS(on)}$ at 4.5V V_{GS}
- Ultra-Low Gate Impedance
- Fully Characterized Avalanche Voltage and Current
- Lead-Free
- RoHS compliant

HEXFET® Power MOSFET

V_{DSS}	$R_{DS(on)}$ max	Qg (typ.)
30V	5.8m Ω @ $V_{GS} = 10V$	15nC



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 20	
I_D @ $T_C = 25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	86 ^④	A
I_D @ $T_C = 100^\circ C$	Continuous Drain Current, V_{GS} @ 10V	61 ^④	
I_{DM}	Pulsed Drain Current ^①	340	
P_D @ $T_C = 25^\circ C$	Maximum Power Dissipation ^⑥	75	W
P_D @ $T_C = 100^\circ C$	Maximum Power Dissipation ^⑥	38	
	Linear Derating Factor	0.5	W/ $^\circ C$
T_J	Operating Junction and	-55 to + 175	$^\circ C$
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ^⑥	—	2.0	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) ^⑤	—	50	
$R_{\theta JA}$	Junction-to-Ambient	—	110	

Notes ^① through ^⑥ are on page 11

ORDERING INFORMATION:

See detailed ordering and shipping information on the last page of this data sheet.

www.irf.com

1

11/23/09

IRLR/U8726PbF

International
IR RectifierStatic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	20	—	mV/°C	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	4.0	5.8	m Ω	$V_{GS} = 10V, I_D = 25A$ ③
		—	5.8	8.0		$V_{GS} = 4.5V, I_D = 20A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	1.35	1.80	2.35	V	$V_{DS} = V_{GS}, I_D = 50\mu A$
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-8.6	—	mV/°C	
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	$V_{DS} = 24V, V_{GS} = 0V$
		—	—	150		$V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$
gfs	Forward Transconductance	73	—	—	S	$V_{DS} = 15V, I_D = 20A$
Q_g	Total Gate Charge	—	15	23	nC	$V_{DS} = 15V$ $V_{GS} = 4.5V$ $I_D = 20A$ See Fig. 15
Q_{gs1}	Pre-Vth Gate-to-Source Charge	—	3.7	—		
Q_{gs2}	Post-Vth Gate-to-Source Charge	—	1.9	—		
Q_{gd}	Gate-to-Drain Charge	—	5.7	—		
Q_{godr}	Gate Charge Overdrive	—	3.7	—		
Q_{sw}	Switch Charge ($Q_{gs2} + Q_{gd}$)	—	7.6	—		
Q_{oss}	Output Charge	—	10	—	nC	$V_{DS} = 15V, V_{GS} = 0V$
R_G	Gate Resistance	—	2.0	3.5	Ω	
$t_{d(on)}$	Turn-On Delay Time	—	12	—	ns	$V_{DD} = 15V, V_{GS} = 4.5V$ ③ $I_D = 20A$ $R_G = 1.8\Omega$ See Fig. 13
t_r	Rise Time	—	49	—		
$t_{d(off)}$	Turn-Off Delay Time	—	15	—		
t_f	Fall Time	—	16	—		
C_{iss}	Input Capacitance	—	2150	—	pF	$V_{GS} = 0V$ $V_{DS} = 15V$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	—	480	—		
C_{riss}	Reverse Transfer Capacitance	—	205	—		

Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy ②	—	120	mJ
I_{AR}	Avalanche Current ①	—	20	A

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	86 ④	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	340		
V_{SD}	Diode Forward Voltage	—	—	1.0	V	$T_J = 25^\circ\text{C}, I_S = 20A, V_{GS} = 0V$ ③
t_{rr}	Reverse Recovery Time	—	24	36	ns	$T_J = 25^\circ\text{C}, I_F = 20A, V_{DD} = 15V$
Q_{rr}	Reverse Recovery Charge	—	52	78	nC	$di/dt = 300A/\mu s$ ③

IRLR/U8726PbF

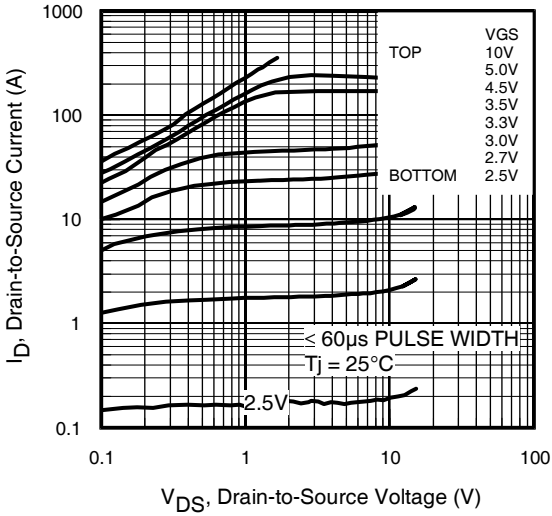


Fig 1. Typical Output Characteristics

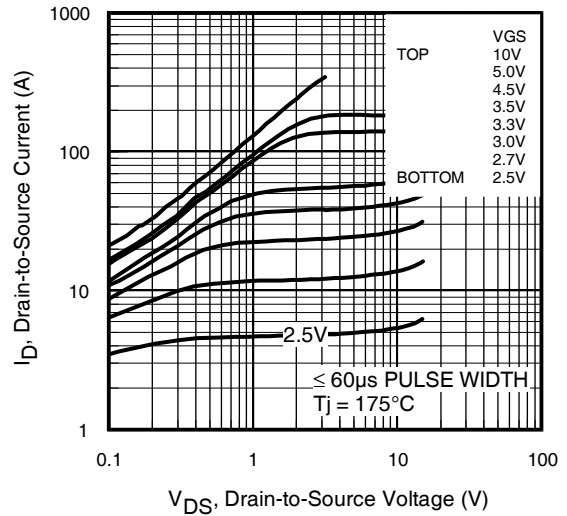


Fig 2. Typical Output Characteristics

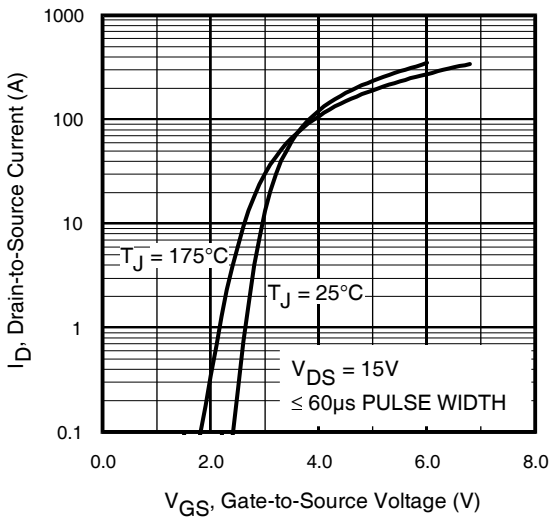


Fig 3. Typical Transfer Characteristics

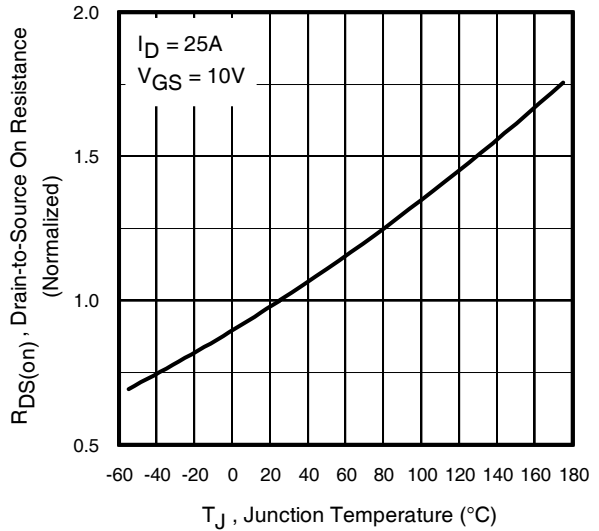


Fig 4. Normalized On-Resistance vs. Temperature

IRLR/U8726PbF

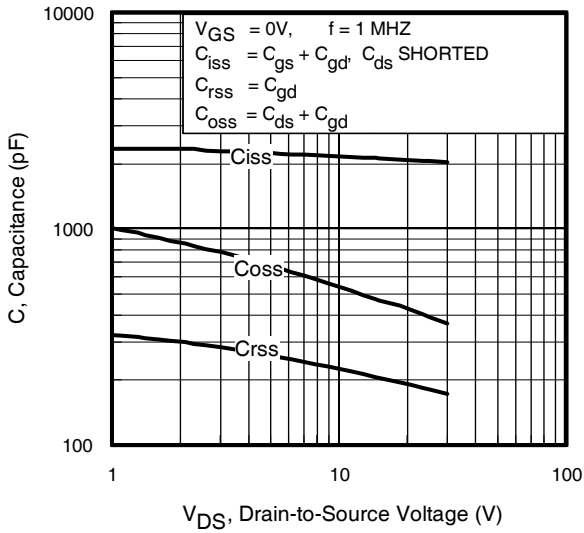


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

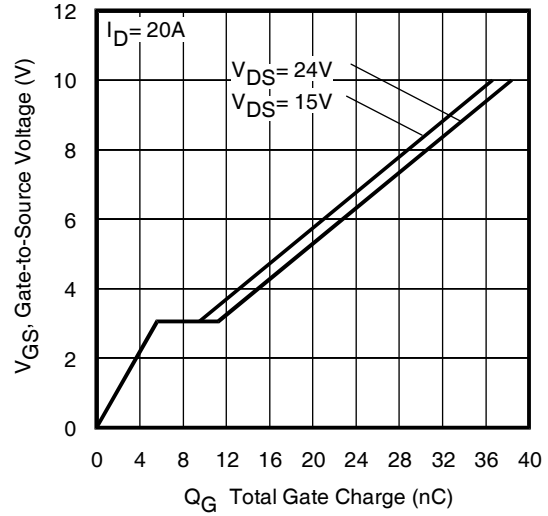


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

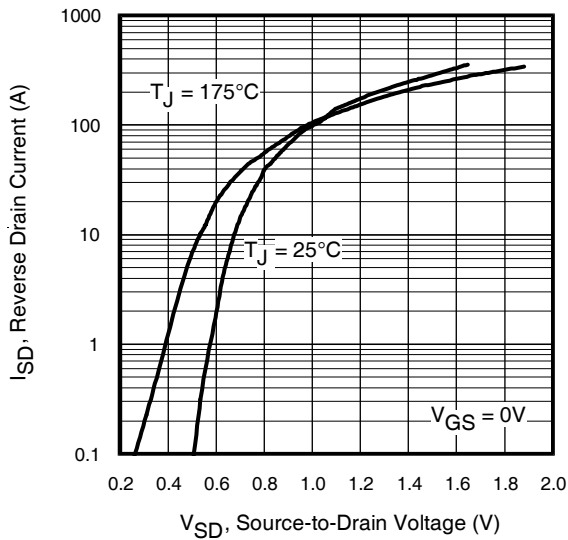


Fig 7. Typical Source-Drain Diode Forward Voltage

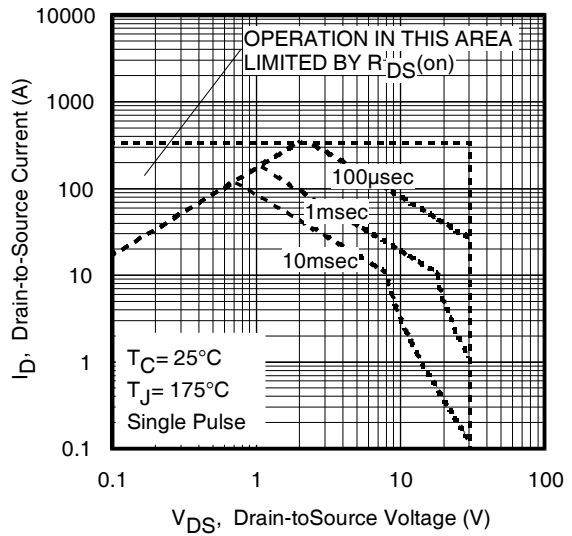


Fig 8. Maximum Safe Operating Area

IRLR/U8726PbF

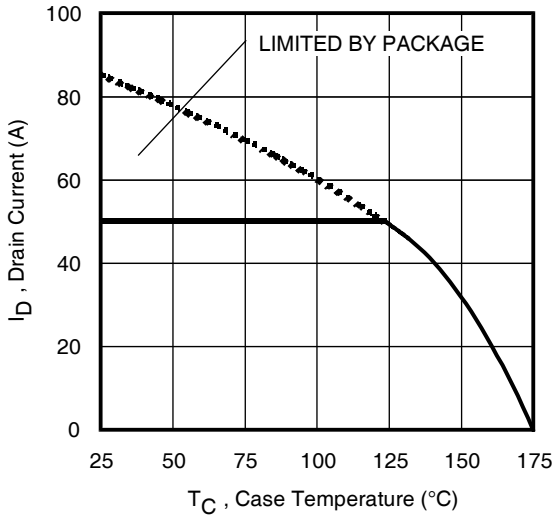


Fig 9. Maximum Drain Current vs. Case Temperature

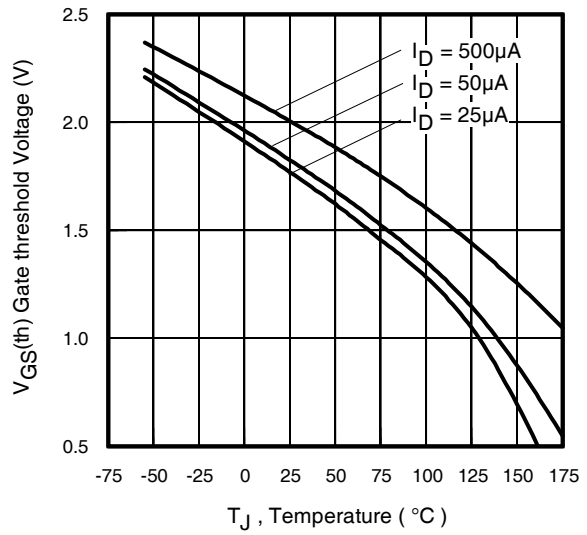


Fig 10. Threshold Voltage vs. Temperature

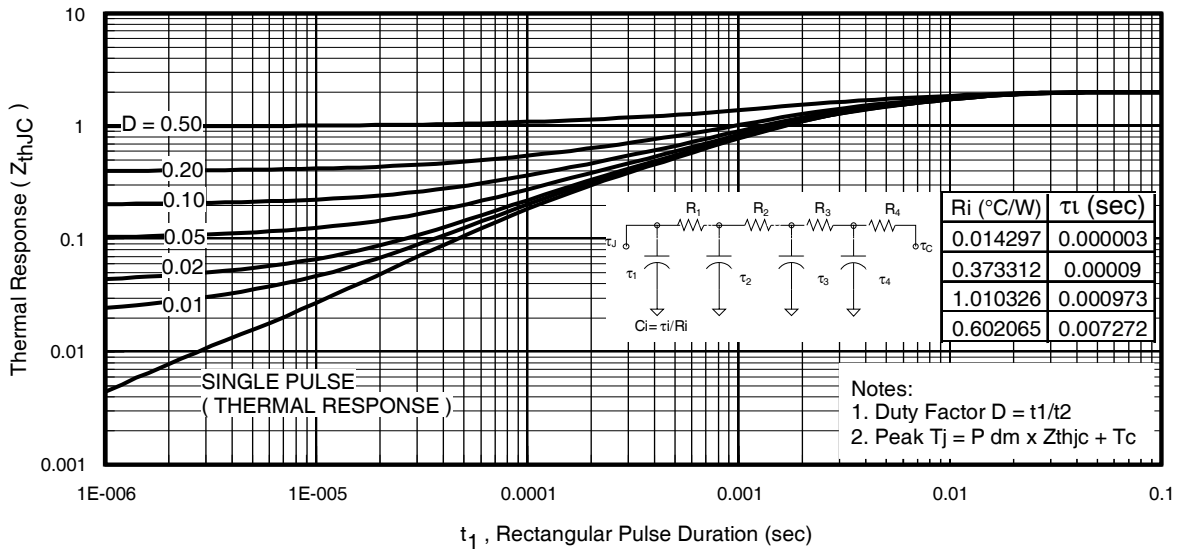


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

IRLR/U8726PbF

International
IR Rectifier

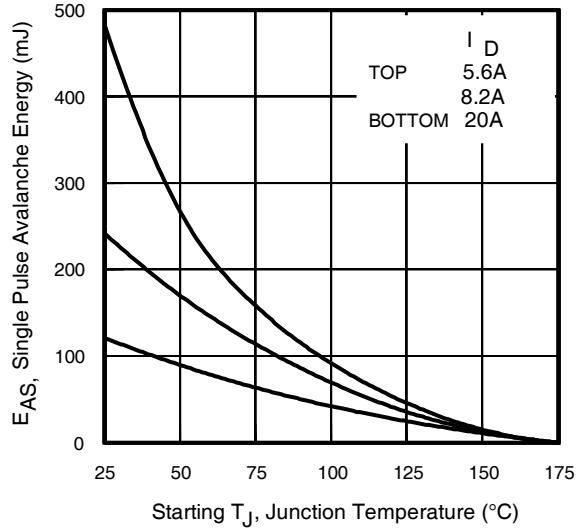


Fig 12a. Maximum Avalanche Energy Vs. Drain Current

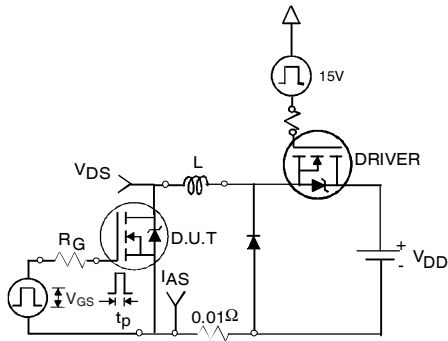


Fig 12b. Unclamped Inductive Test Circuit

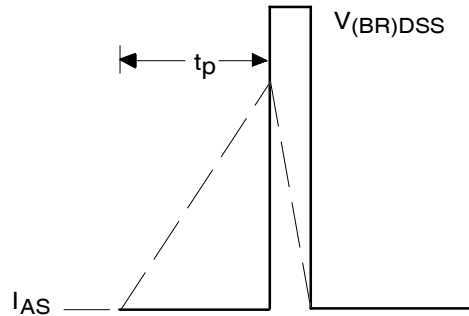


Fig 12c. Unclamped Inductive Waveforms

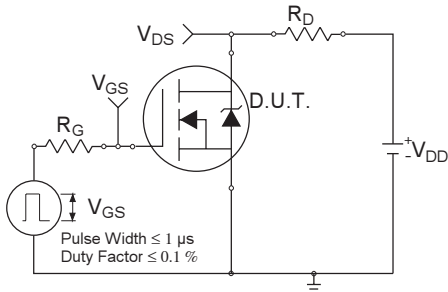


Fig 13a. Switching Time Test Circuit

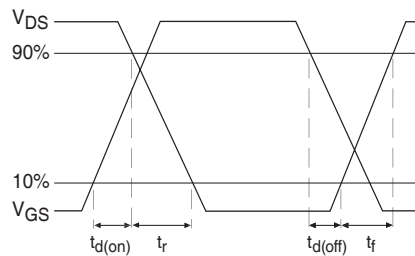


Fig 13b. Switching Time Waveforms

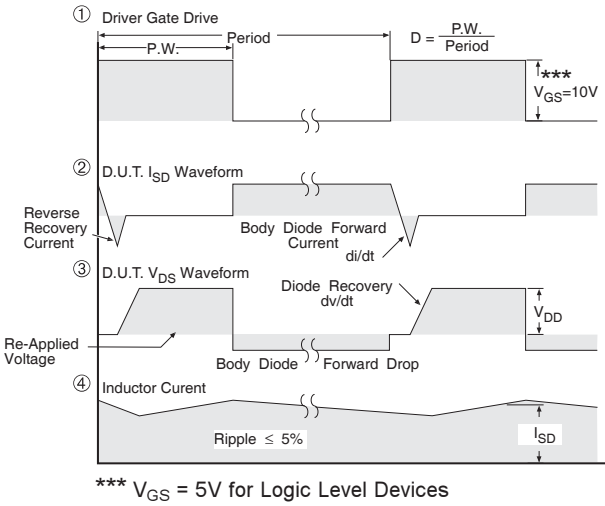
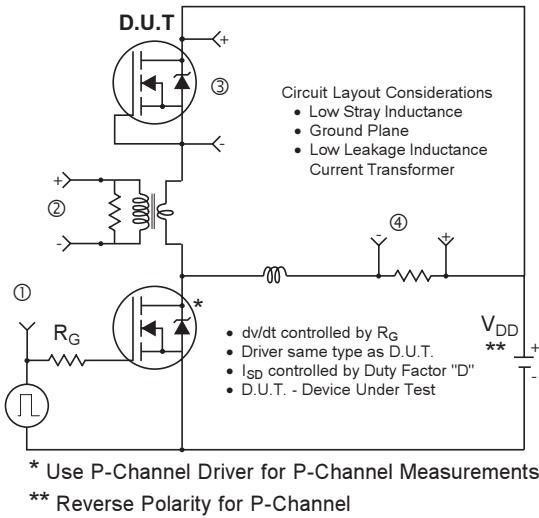


Fig 14. Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

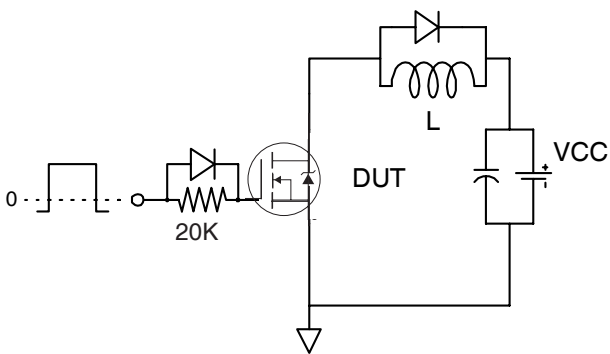


Fig 15. Gate Charge Test Circuit

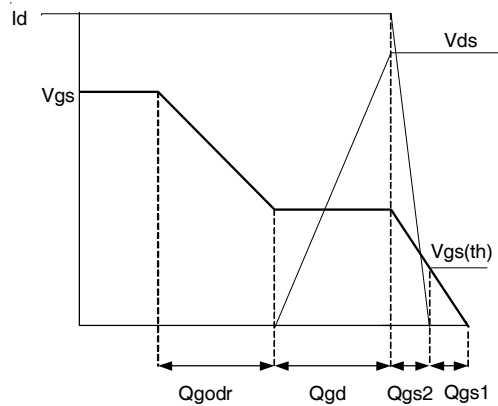


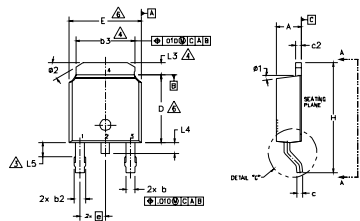
Fig 16. Gate Charge Waveform

IRLR/U8726PbF

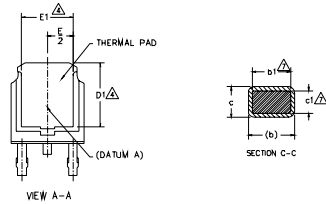
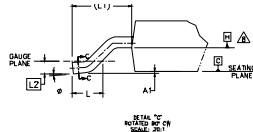
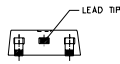


D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - 2.- DIMENSIONS ARE SHOWN IN INCHES (MILLIMETERS)
 - 3.- LEAD DIMENSION UNCONTROLLED IN L.S.
 - 4.- DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
 - 5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
 - 6.- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
 - 7.- DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
 - 8.- DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
 - 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.



SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1	-	0.13	-	.005	
b	0.64	0.89	.025	.035	7
b1	0.65	0.79	.025	.031	
b2	0.76	1.14	.030	.045	
b3	4.95	5.46	.195	.215	4
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	7
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	6
D1	5.21	-	.205	-	4
E	6.35	6.73	.250	.265	6
E1	4.32	-	.170	-	4
e	2.29 BSC		.090 BSC		
H	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2.34 BSC		.093 REF.		
L2	0.51 BSC		.020 BSC		
L3	0.89	1.27	.035	.050	4
L4	-	1.02	-	.040	
L5	1.14	1.52	.045	.060	3
ø	0'	10'	0'	10'	
ø1	0'	15'	0'	15'	
ø2	25'	35'	25'	35'	

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBT & CoPAK

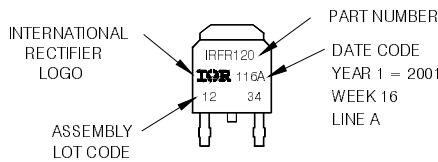
- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

D-Pak (TO-252AA) Part Marking Information

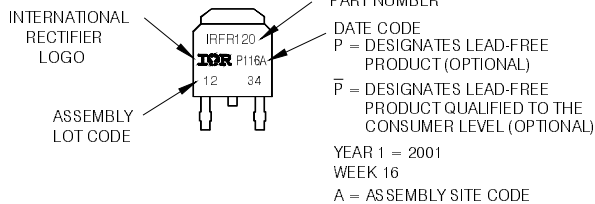
EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW 16, 2001
IN THE ASSEMBLY LINE 'A'

Note: 'P' in assembly line position
indicates 'Lead-Free'

'P' in assembly line position indicates
'Lead-Free' qualification to the consumer-level



OR



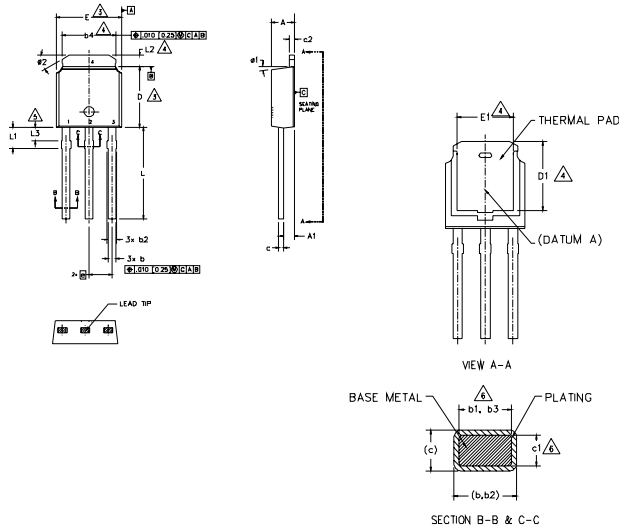
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>



IRLR/U8726PbF

I-Pak (TO-251AA) Package Outline

Dimensions are shown in millimeters (inches)



- NOTES:
- 1- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - 2- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS]
 - 3- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
 - 4- THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
 - 5- LEAD DIMENSION UNCONTROLLED IN L3.
 - 6- DIMENSION b1, b3 & c1 APPLY TO BASE METAL ONLY.
 - 7- OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA (Date 06/02).
 - 8- CONTROLLING DIMENSION : INCHES.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1	0.89	1.14	.035	.045	
b	0.64	0.89	.025	.035	
b1	0.65	0.79	.025	.031	6
b2	0.76	1.14	.030	.045	
b3	0.76	1.04	.030	.041	6
b4	4.95	5.46	.195	.215	4
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	6
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	3
D1	5.21	-	.205	-	4
E	6.35	6.73	.250	.265	3
E1	4.32	-	.170	-	4
e	2.29	BSC	.090	BSC	
L	8.89	9.65	.350	.380	
L1	1.91	2.29	.045	.090	
L2	0.89	1.27	.035	.050	4
L3	1.14	1.52	.045	.060	5
#1	0"	15"	0"	15"	
#2	25"	35"	25"	35"	

LEAD ASSIGNMENTS

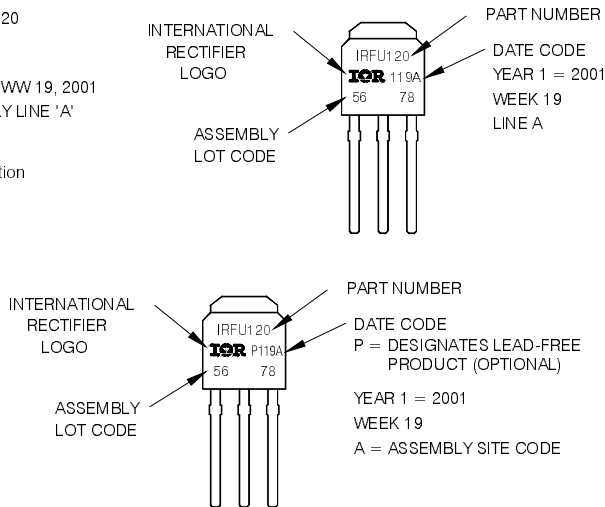
- HEXFET
- 1.- GATE
 - 2.- DRAIN
 - 3.- SOURCE
 - 4.- DRAIN

I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120
WITH ASSEMBLY
LOT CODE 5678
ASSEMBLED ON WW 19, 2001
IN THE ASSEMBLY LINE 'A'

Note: 'P' in assembly line position
indicates Lead-Free'

OR



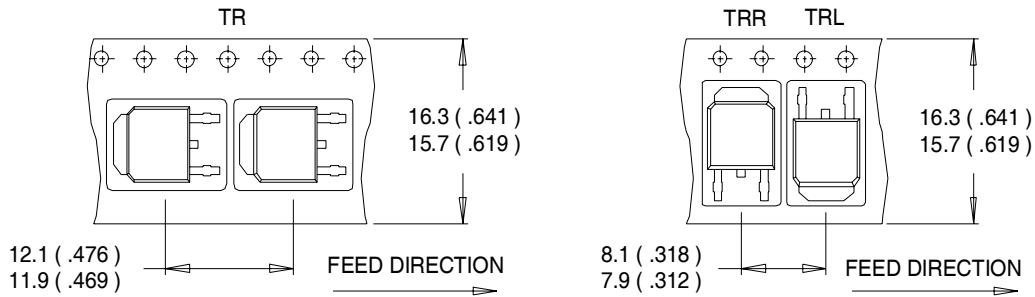
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>
www.irf.com

IRLR/U8726PbF

International
IR Rectifier

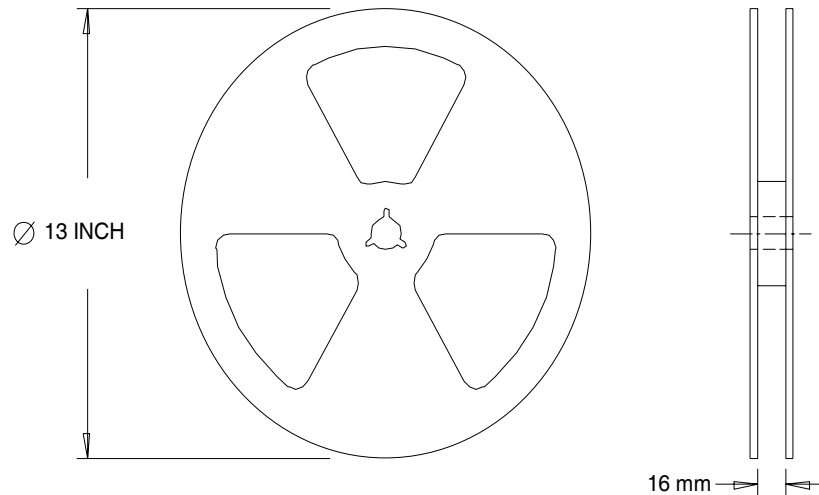
D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. OUTLINE CONFORMS TO EIA-481.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

International
 Rectifier

IRLR/U8726PbF

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRLR8726PBF	D-PAK	Tube/Bulk	75	
IRLR8726TRPBF	D-PAK	Tape and Reel	2000	
IRLU8726PBF	I-PAK	Tube/Bulk	75	

Qualification information[†]

D-PAK

Qualification level	Consumer ^{††}
Moisture Sensitivity Level	MSL1
	(per JEDEC J-STD-020D ^{†††})
RoHS compliant	Yes

I-PAK

Qualification level	Industrial
Moisture Sensitivity Level	Not applicable
RoHS compliant	Yes

† Qualification standards can be found at International Rectifier's web site <http://www.irf.com/product-info/reliability>

†† Higher qualification ratings may be available should the user have such requirements. Please contact your

International Rectifier sales representative for further information: <http://www.irf.com/whoto-call/salesrep/>

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^\circ\text{C}$, $L = 0.605\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 20\text{A}$.
- ③ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ④ Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 50A.
- ⑤ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ⑥ R_θ is measured at T_J approximately at 90°C

Data and specifications subject to change without notice.

International
 Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information.11/2009

IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office (www.infineon.com).

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we strictly control the quality of products and services. Welcome your RFQ to

Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.